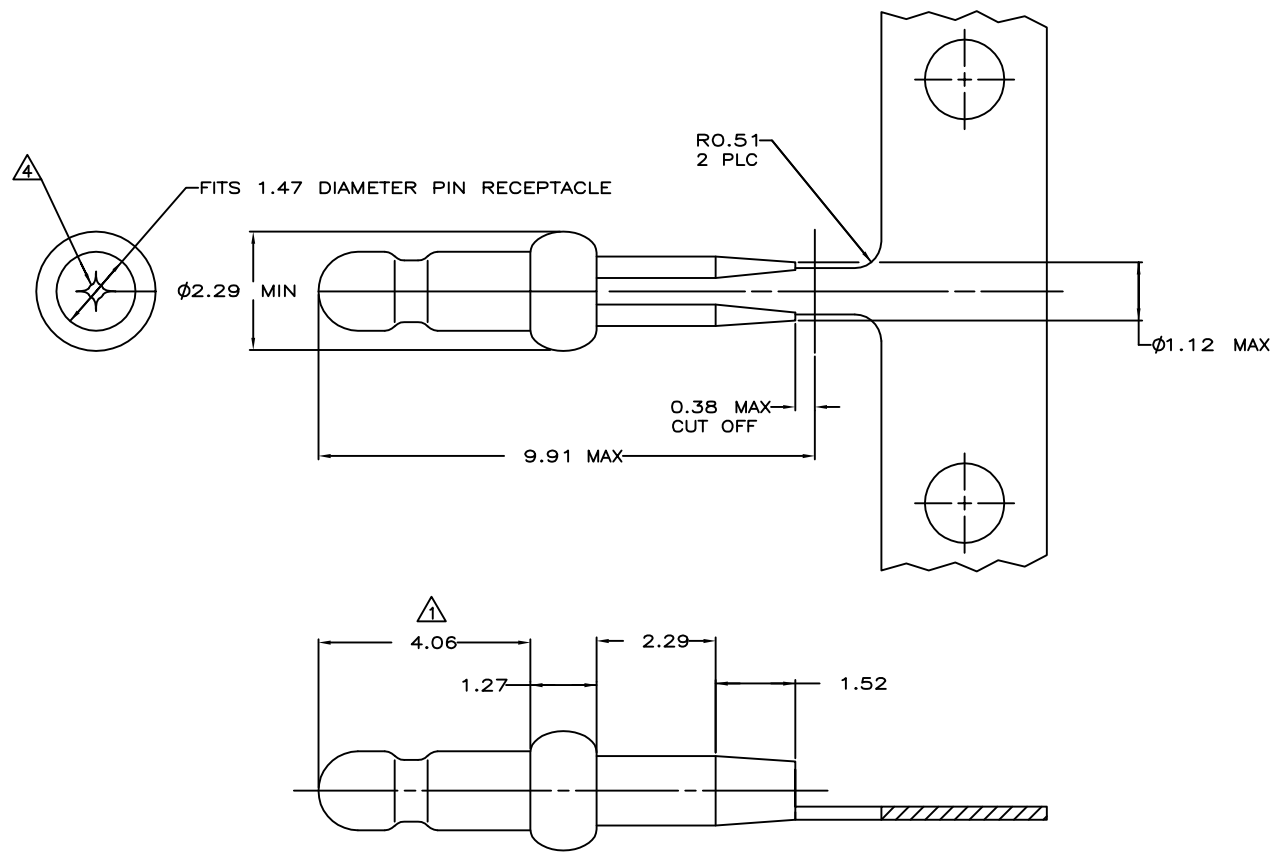
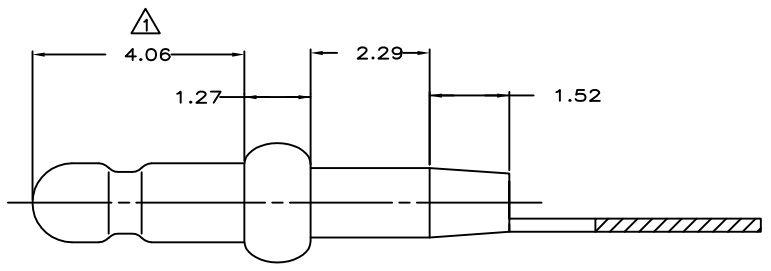
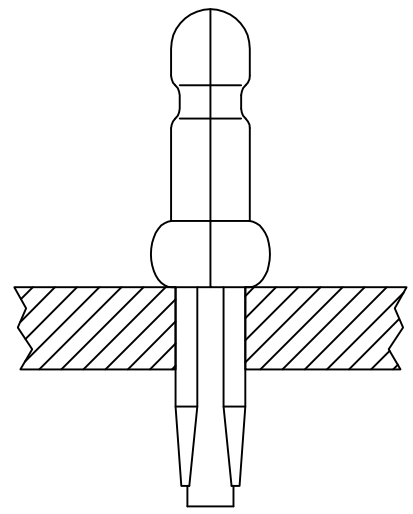


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REVISIONS					
P	LTR	DESCRIPTION	DATE	DM	APD
AP3		REVISED PER EOR-17-013047	12SEP17	J.Z	D.Z



- ⚠ 0.00076 MIN GOLD PLATING IN THIS AREA WITH 0.00381 MIN MATTE TIN LEAD ON THE REMAINDER, BOTH OVER 0.00127 MIN NICKEL UNDERPLATE.
- 2. FITS 1.17 - 1.27 DIAMETER HOLE IN A 1.57 OR 2.36 PRINTED CIRCUIT BOARD.
- 3. PARTS TO COMPLY WITH AMP SOLDERABILITY SPECIFICATION 109-11-3.
- ⚠ 0.05 - 0.25 DIAMETER OPENING REQUIRED IN TIP OF PIN.
- 5. APPLICATOR FEED: 8.00 - 8.26
- ⚠ 0.00076 MIN GOLD PLATING IN THIS AREA WITH 0.00381 MIN MATTE TIN ON THE REMAINDER, BOTH OVER 0.00127 MIN NICKEL UNDERPLATE.



	⚠	3-60802-1
	PRE TIN	60802-2
OBSOLETE	⚠	60802-1
	FINISH	PART NUMBER

0.13	.005	1.17	.046	2.29	.090	9.91	.390
0.05	.002	1.12	.044	1.57	.062	8.26	.325
0.00381	0.000150	0.51	.020	1.52	.060	8.00	.315
0.00127	0.000050	0.38	.015	1.47	.058	4.06	.160
0.00076	0.000030	0.25	.010	1.27	.050	2.36	.093
MM	IN	MM	IN	MM	IN	MM	IN

CONVERSION TABLE

METRIC

THIS DRAWING IS A CONTROLLED DOCUMENT.

DM: T. BECK 7-28-97	NAME: TE Connectivity
CHK: R. SWING 7-28-97	
APD: A. BEDDICK 9-10-97	
PRODUCT SPEC: 108-1025	
APPLICATION SPEC: 114-1008	
WEIGHT: 0.000000	RESTRICTED TO: -
MATERIAL: 0.25 PH BRZ	
FINISH: SEE TABLE	
CUSTOMER DRAWING	SCALE: 15:1 SHEET 1 of 1 REV AP3

单击下面可查看定价，库存，交付和生命周期等信息

[>>TE Connectivity\(泰科\)](#)